

## SSW Screen and Stencil Wipes

SSW remove both solder pastes and adhesives with high efficiency. The wipes are made from high wet strength fabric, pre-saturated with a formulated solvent based cleaner.

- Removes solder and adhesive residues; ideal for cleaning stencils and related equipment
- Available in a re-sealable tub; ideal for use in manufacturing environments
- Large wipe size; efficient cleaning of larger surface areas
- Non-flammable solvent blend; eliminates the use of flammable materials

|                                             |                                      |                          |
|---------------------------------------------|--------------------------------------|--------------------------|
| <b>Approvals</b>                            | <b>RoHS Compliant (2015/863/EU):</b> | <b>Yes</b>               |
| <b>Typical Properties<br/>(Concentrate)</b> | Boiling Point (°C)                   | >100                     |
|                                             | Flash Point                          | 61                       |
|                                             | Density (g/ml)                       | 0.85                     |
|                                             | Wipe Material                        | 41gsm hydrospun material |

| <u><b>Description</b></u>       | <u><b>Packaging</b></u> | <u><b>Order Code</b></u> | <u><b>Shelf Life</b></u> |
|---------------------------------|-------------------------|--------------------------|--------------------------|
| <u>Screen and Stencil Wipes</u> | 100 Wipe Tub            | SSW100                   | 24 Months                |

### Directions for Use

SSW enable easy removal, by hand, of solder pastes and adhesive deposits from screens and stencils after screen printing. The wipes exhibit excellent removal of a wide range of solder pastes and adhesives. We recommend that Vinyl or Nitrile disposable gloves are worn when using the product to avoid defatting of the skin, as well as protecting against the effects of lead solder pastes and one part epoxy based adhesives.

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